

METHOD AND APPARATUS FOR WAFER MECHANICAL STRESS MONITORING AND WAFER THERMAL STRESS MONITORING

ABSTRACT OF THE DISCLOSURE

A chemical mechanical planarization (CMP) system is provided. The CMP system includes a wafer carrier configured to support a wafer during a planarization process, the wafer carrier including a sensor configured to detect a signal indicating a stress being experienced by the wafer during planarization. A computing device in communication with the sensor is included. The computing device is configured to translate the signal to generate a stress map for analysis. A stress relief device responsive to a signal received from the computing device is included. The stress relief device is configured to relieve the stress being experienced by the wafer.